
RAD-TOLERANT CLASS-V REGULATING PULSE WIDTH MODULATOR

FEATURES

- QML-V Qualified, SMD 5962-89511
- Rad-Tolerant: 30 kRad (Si) TID ⁽¹⁾
- 8-V to 35-V Operation
- 5.1-V Buried Zener Reference Trimmed to $\pm 0.75\%$
- 100-Hz to 400-kHz Oscillator Range
- Separate Oscillator Sync Terminal
- Adjustable Deadtime Control
- Internal Soft Start
- Pulse-by-Pulse Shutdown
- Input Undervoltage Lockout With Hysteresis
- Latching PWM to Prevent Multiple Pulses
- Dual Source/Sink Output Drivers
- Low Cross Conduction Output Stage
- Tighter Reference Specifications

(1) Radiation tolerance is a typical value based upon initial device qualification with dose rate = 10 mrad/sec. Radiation Lot Acceptance Testing is available - contact factory for details.

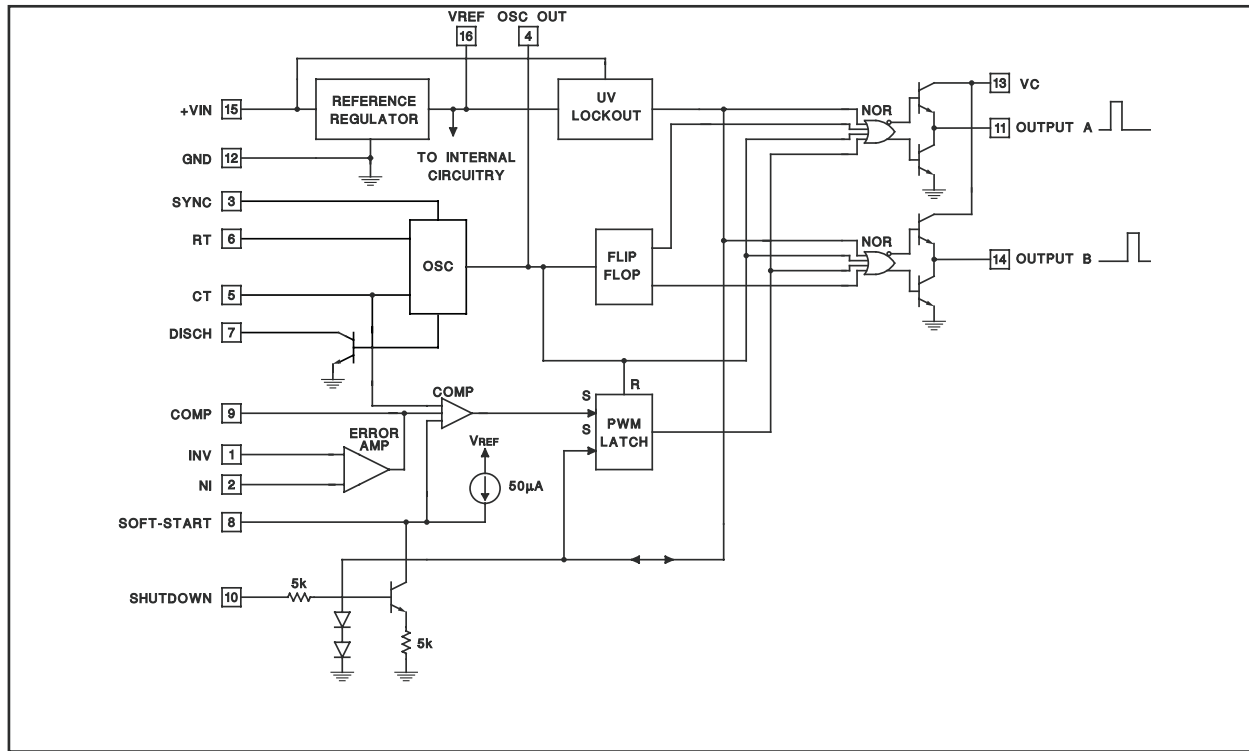
DESCRIPTION

The UC1525B pulse width modulator integrated circuit is designed to offer improved performance and lowered external parts count when used in designing all types of switching power supplies. The on-chip 5.1-V buried zener reference is trimmed to $\pm 0.75\%$, and the input common-mode range of the error amplifier includes the reference voltage, eliminating external resistors. A sync input to the oscillator allows multiple units to be slaved or a single unit to be synchronized to an external system clock. A single resistor between the CT and the discharge terminals provide a wide range of dead-time adjustment. These devices also feature built-in soft-start circuitry with only an external timing capacitor required. A shutdown terminal controls both the soft-start circuitry and the output stages, providing instantaneous turn off through the PWM latch with pulsed shutdown, as well as soft-start recycle with longer shutdown commands. These functions are also controlled by an undervoltage lockout which keeps the outputs off and the soft-start capacitor discharged for sub-normal input voltages. This lockout circuitry includes approximately 500 mV of hysteresis for jitter-free operation. Another feature of these PWM circuits is a latch following the comparator. Once a PWM pulse has been terminated for any reason, the outputs remain off for the duration of the period. The latch is reset with each clock pulse. The output stages are totem-pole designs capable of sourcing or sinking in excess of 200 mA. The UC1525B output stage features NOR logic, giving a LOW output for an OFF state.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

BLOCK DIAGRAM



This device has limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ORDERING INFORMATION⁽¹⁾

T _A	PACKAGE ⁽²⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-55°C to 125°C	FK	5962-8951106V2A	UC1525BFK-SP

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.
- (2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

ABSOLUTE MAXIMUM RATINGS⁽¹⁾⁽²⁾

over operating free-air temperature range (unless otherwise noted)

+V _{IN}	Supply voltage		40 V
V _C	Collector supply voltage		40 V
	Logic inputs		–0.3 V to 5.5 V
V _I	Analog inputs		–0.3 V to V _{IN}
I _O	Output current, source or sink		500 mA
	Reference output current		50 mA
	Oscillator charging current		5 mA
P _D	Power dissipation	T _A = 25°C	1000 mW
		T _C = 25°C	2000 mW
T _J	Operating junction temperature		–55°C to 150°C
T _{stg}	Storage temperature range		–65°C to 150°C
T _{lead}	Lead temperature (soldering, 10 seconds)		300°C

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltages are with respect to ground. Currents are positive into, negative out of the specified terminal.

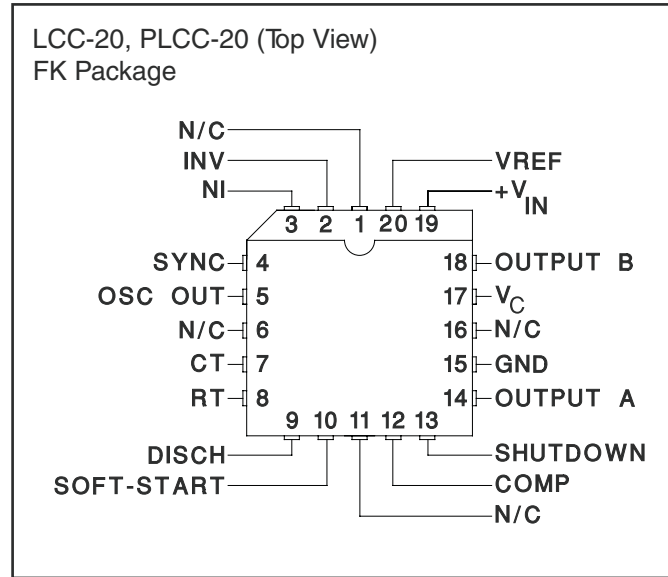
RECOMMENDED OPERATING CONDITIONS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
+V _{IN}	Input voltage	8	35	V
V _C	Collector supply voltage	4.5	35	V
	Sink/source load current (steady state)	0	100	mA
	Sink/source load current (peak)	0	400	mA
	Reference load current	0	20	mA
	Oscillator frequency range	0.1	400	kHz
	Oscillator timing resistor	2	150	kΩ
	Oscillator timing capacitor	0.001	0.1	μF
	Dead time resistor range	0	500	Ω

- (1) Range over which the device is functional and parameter limits are specified.

CONNECTION DIAGRAM



ELECTRICAL CHARACTERISTICS

$V_{IN} = 20\text{ V}$, $T_A = T_J = -55^\circ\text{C}$ to 125°C (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Reference Section					
Output voltage	$T_J = 25^\circ\text{C}$	5.062	5.10	5.138	V
Line regulation	$V_{IN} = 8\text{ V}$ to 35 V		5	10	mV
Load regulation	$I_L = 0\text{ mA}$ to 20 mA		7	15	mV
Temperature stability ⁽¹⁾	Over operating range		10	50	mV
Total output variation	Over line, load, and temperature	5.036		5.164	V
Short-circuit current	$V_{REF} = 0\text{ V}$, $T_J = 25^\circ\text{C}$		80	100	mA
Output noise voltage ⁽¹⁾	$10\text{ Hz} \leq f \leq 10\text{ kHz}$, $T_J = 25^\circ\text{C}$		40	200	μVrms
Oscillator Section					
Initial accuracy ⁽²⁾	$T_J = 25^\circ\text{C}$		± 2	± 6	%
Voltage stability ⁽²⁾	$V_{IN} = 8\text{ V}$ to 35 V		± 0.3	± 1	%
Temperature stability ⁽¹⁾⁽²⁾	Over operating range		± 3	± 6	%
Minimum frequency	$R_T = 200\text{ k}\Omega$, $C_T = 0.1\text{ }\mu\text{F}$			120	Hz
Maximum frequency	$R_T = 2\text{ k}\Omega$, $C_T = 470\text{ pF}$	400			kHz
Current mirror	$I_{RT} = 2\text{ mA}$	1.7	2.	2.2	mA
Clock amplitude ⁽²⁾		3	3.5		V
Clock width ⁽²⁾	$T_J = 25^\circ\text{C}$	0.3	0.5	1	μs
Sync threshold		1.2	2	2.8	V
Sync input current	Sync = 3.5 V		1	2.5	mA

(1) Parameters ensured by design and/or characterization, if not production tested.

(2) Tested at $f_{osc} = 40\text{ kHz}$ ($R_T = 3.6\text{ k}\Omega$, $C_T = 0.01\text{ }\mu\text{F}$, $R_D = 0\text{ }\Omega$).
Approximate oscillator frequency is defined by: $f = 1/(C_T (0.7 \times R_T + 3R_D))$.

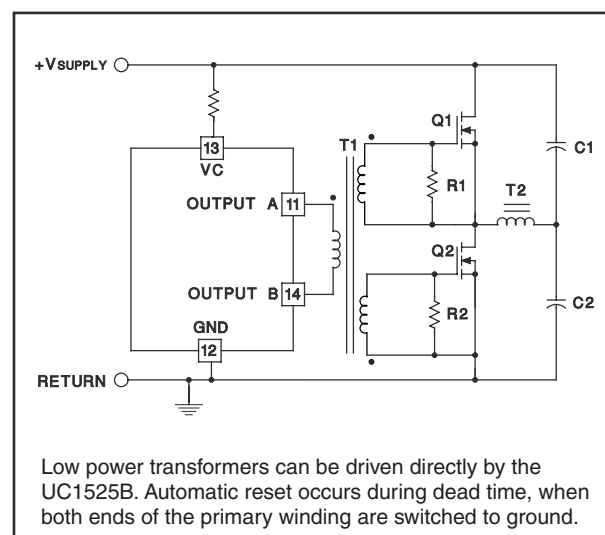
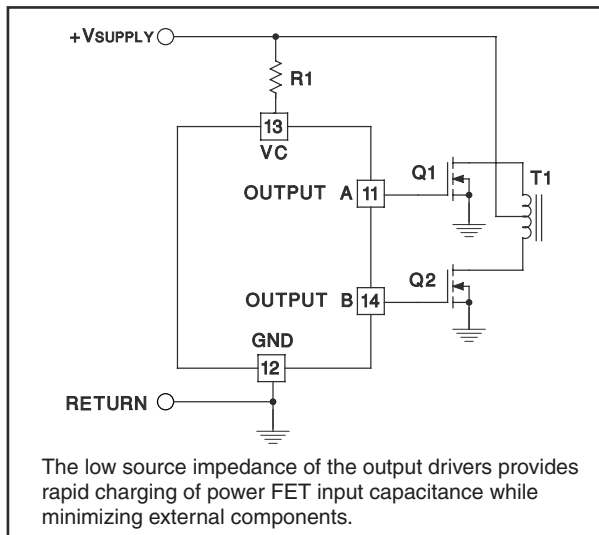
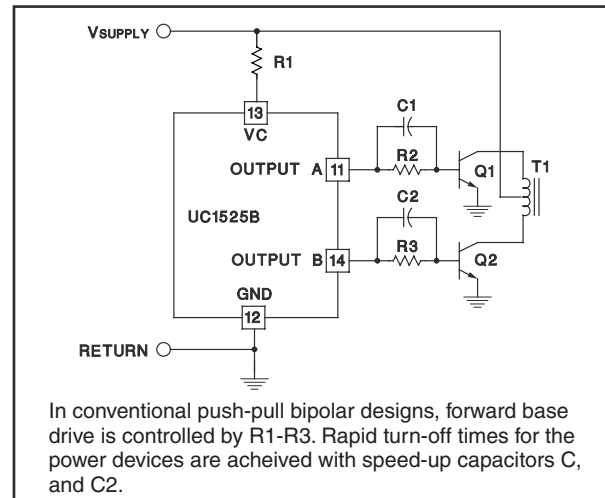
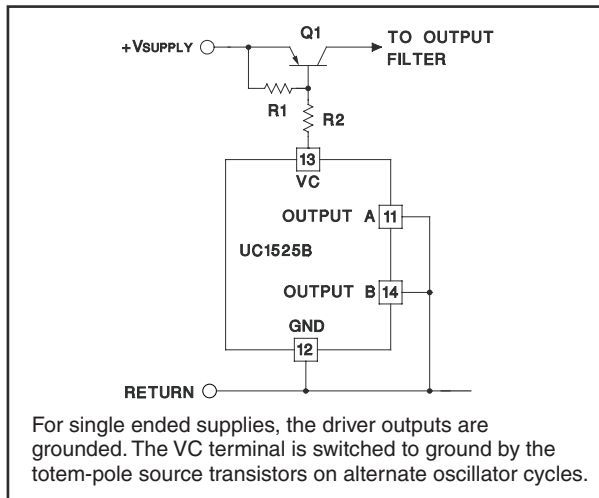
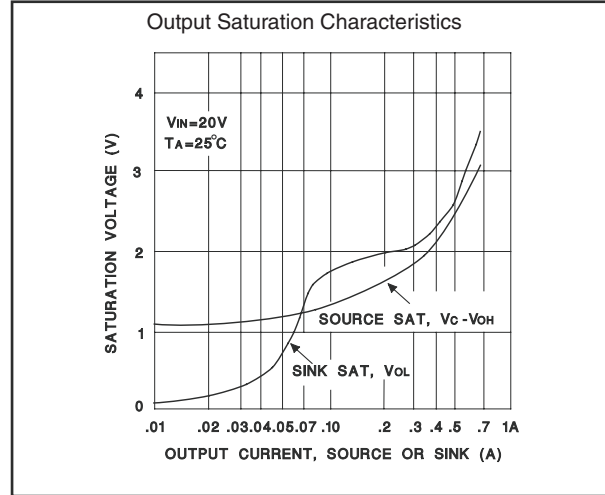
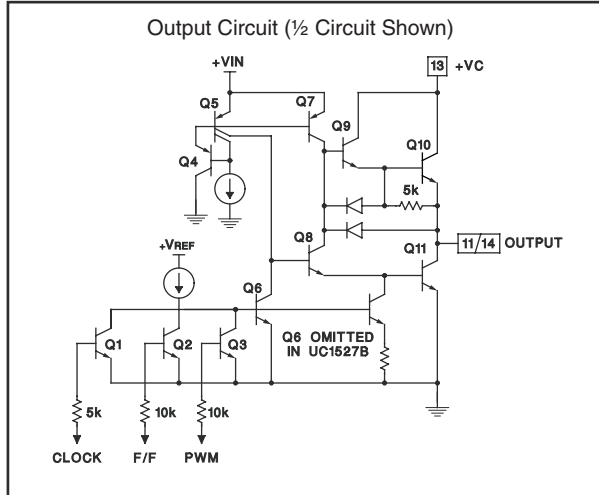
ELECTRICAL CHARACTERISTICS (continued)
 $V_{IN} = 20\text{ V}$, $T_A = T_J = -55^\circ\text{C}$ to 125°C (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Error Amplifier Section ($V_{CM} = 5.1\text{ V}$)					
Input offset voltage			0.5	5	mV
Input bias current			1	10	μA
Input offset current				1	μA
DC open loop gain	$R_L \geq 10\text{ M}\Omega$	60	75		dB
Gain-bandwidth product ⁽³⁾	$A_V = 0\text{ dB}$, $T_J = 25^\circ\text{C}$	1	2		MHz
Output low level			0.2	0.5	V
Output high level		3.8	5.6		V
Common mode rejection	$V_{CM} = 1.5\text{ V}$ to 5.2 V	60	75		dB
Supply voltage rejection	$V_{IN} = 8\text{ V}$ to 35 V	50	60		dB
PWM Comparator					
Minimum duty cycle				0	%
Maximum duty cycle ⁽⁴⁾		45	49		%
Input threshold ⁽⁴⁾	Zero duty cycle	0.7	0.9		V
Input threshold ⁽⁴⁾	Maximum duty cycle		3.3	3.6	V
Input bias current			0.05		μA
Shutdown Section					
Soft start current	$V_{SHUTDOWN} = 0\text{ V}$, $V_{SOFTSTART} = 0\text{ V}$	25	50	80	μA
Soft start low level	$V_{SHUTDOWN} = 2.5\text{ V}$		0.4	0.7	V
Shutdown threshold	To outputs, $V_{SOFTSTART} = 5.1\text{ V}$, $T_J = 25^\circ\text{C}$	0.6	0.8	1	V
Shutdown input current	$V_{SHUTDOWN} = 2.5\text{ V}$		0.4	1	mA
Shutdown delay ⁽³⁾	$V_{SHUTDOWN} = 2.5\text{ V}$, $T_J = 25^\circ\text{C}$		0.2	0.5	μs
Output Drivers (Each Output) ($V_C = 20\text{ V}$)					
Output low level	$I_{SINK} = 20\text{ mA}$		0.2	0.4	V
	$I_{SINK} = 100\text{ mA}$		1	2	
Output high level	$I_{SOURCE} = 20\text{ mA}$	18	19		V
	$I_{SOURCE} = 100\text{ mA}$	17	18		
Undervoltage lockout	V_{COMP} and $V_{SOFTSTART} = \text{High}$	6	7	8	V
Collector leakage	$V_C = 35\text{ V}$			200	μA
Rise time ⁽³⁾	$C_L = 1\text{ nF}$, $T_J = 25^\circ\text{C}$		100	600	ns
Fall time ⁽³⁾	$C_L = 1\text{ nF}$, $T_J = 25^\circ\text{C}$		50	300	ns
Cross conduction charge	Per cycle, $T_J = 25^\circ\text{C}$		30		nC
Total Standby Current					
Supply current	$V_{IN} = 35\text{ V}$		14	20	mA

(3) Parameters ensured by design and/or characterization, if not production tested.

(4) Tested at $f_{osc} = 40\text{ kHz}$ ($R_T = 3.6\text{ k}\Omega$, $C_T = 0.01\text{ }\mu\text{F}$, $R_D = 0\text{ }\Omega$).
Approximate oscillator frequency is defined by: $f = 1/(C_T (0.7 \times R_T + 3R_D))$.

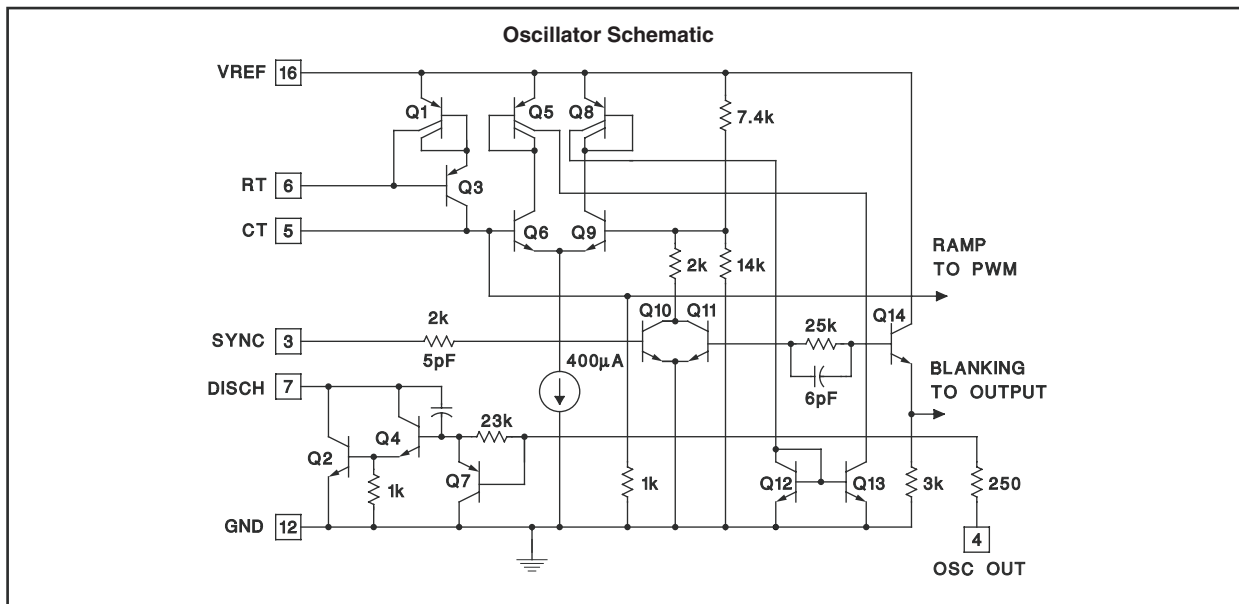
PRINCIPLES OF OPERATION AND TYPICAL CHARACTERISTICS



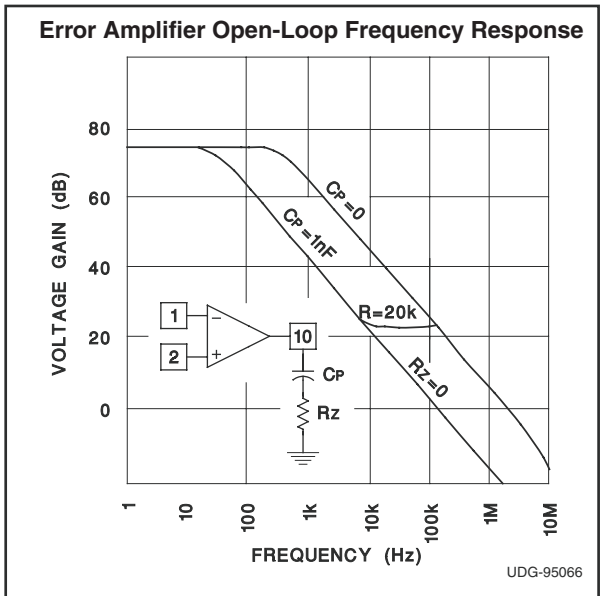
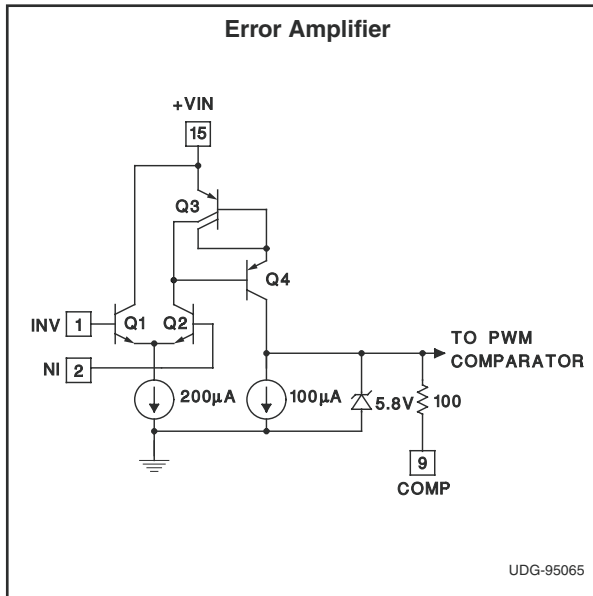
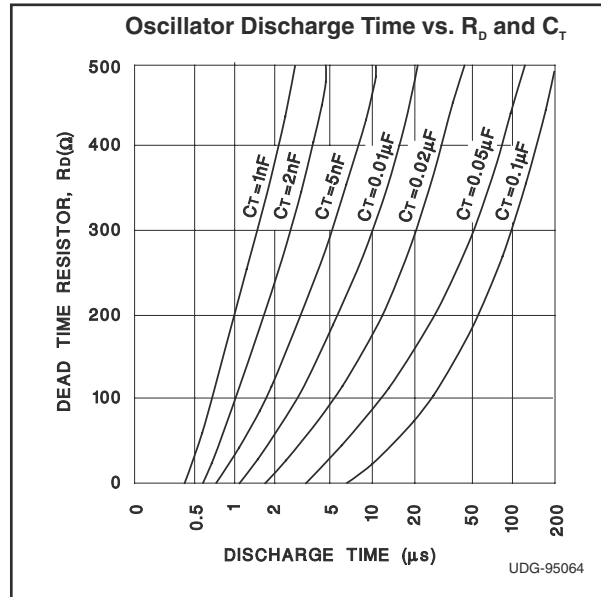
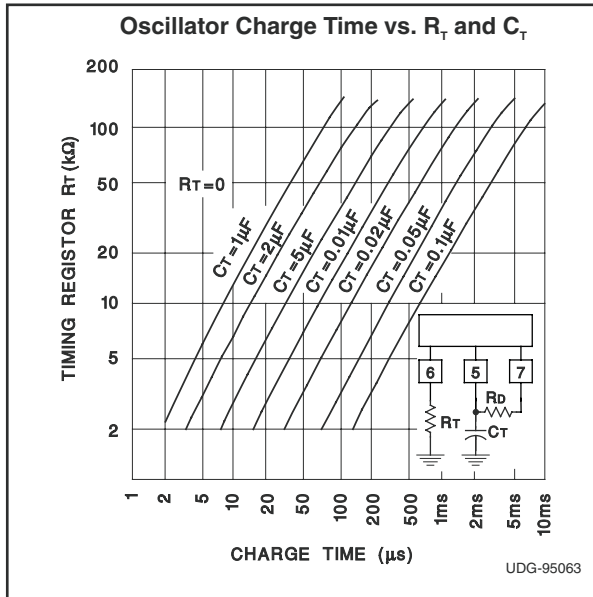
PRINCIPLES OF OPERATION AND TYPICAL CHARACTERISTICS (continued)

Since both the compensation and soft-start terminals (Pins 9 and 8) have current source pullups, either can readily accept a pulldown signal, which only has to sink a maximum of 100 μA to turn off the outputs. This is subject to the added requirement of discharging whatever external capacitance may be attached to these pins.

An alternate approach is the use of the shutdown circuitry of Pin 10, which has been improved to enhance the available shutdown options. Activating this circuit by applying a positive signal on Pin 10 performs two functions: the PWM latch is immediately set providing the fastest turn-off signal to the external soft-start capacitor. If the shutdown command is short, the PWM signal is terminated without significant discharge of the soft-start capacitor, thus, allowing, for example, a convenient implementation of pulse-by-pulse current limiting. Holding Pin 10 high for a longer duration, however, ultimately discharges this external capacitor, recycling slow turn-on upon release.

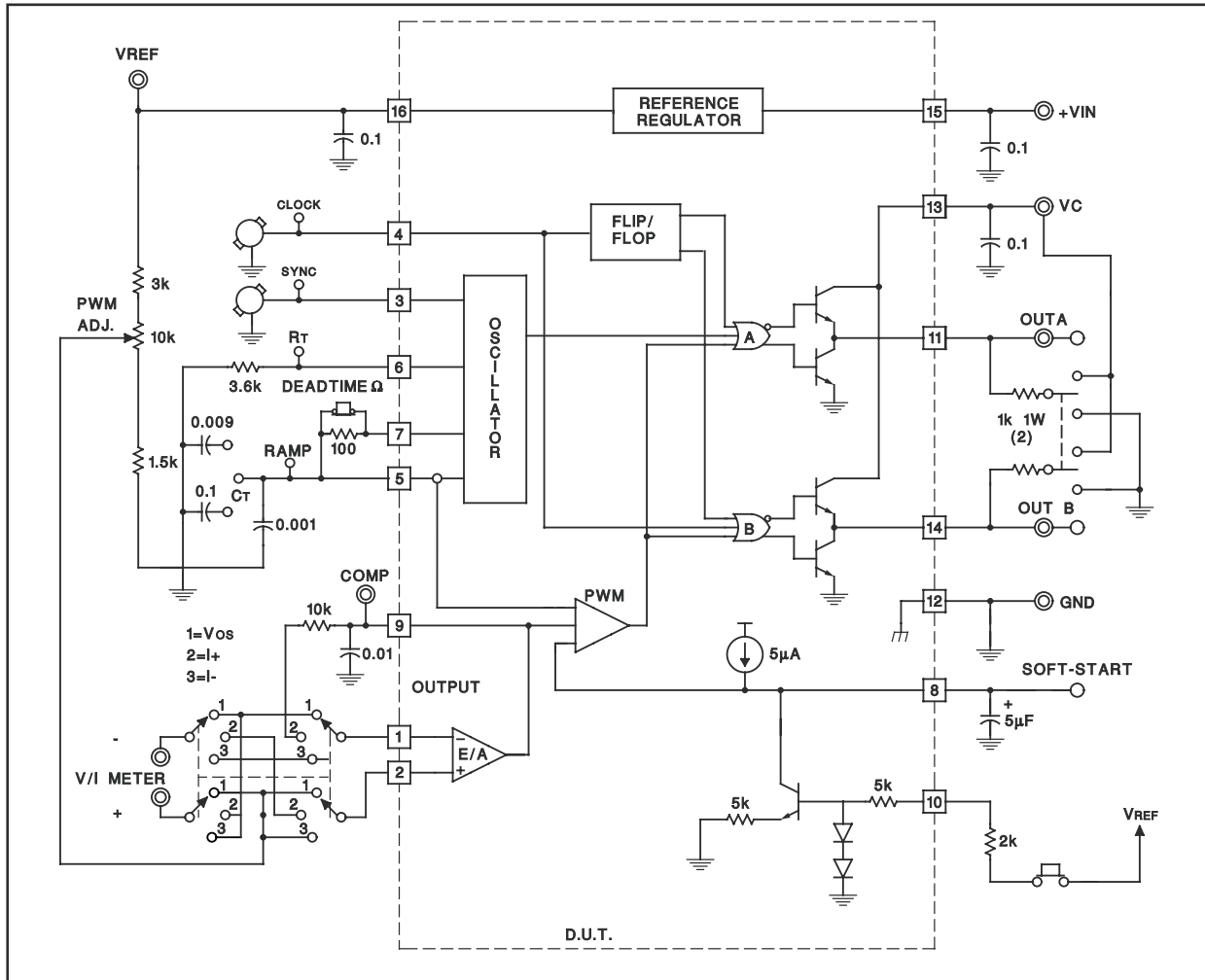


PRINCIPLES OF OPERATION AND TYPICAL CHARACTERISTICS (continued)



PRINCIPLES OF OPERATION AND TYPICAL CHARACTERISTICS (continued)

LAB TEST FIXTURE



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-8951105V2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-8951105VEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
5962-8951106V2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF UC1525B-SP :

- Catalog: [UC1525B](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
RF/IF and ZigBee® Solutions	www.ti.com/lprf

Applications

Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Transportation and Automotive	www.ti.com/automotive
Video and Imaging	www.ti.com/video
Wireless	www.ti.com/wireless-apps

TI E2E Community Home Page

e2e.ti.com

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2011, Texas Instruments Incorporated